



Revision History

<u>Rev. No.</u>	<u>History</u>	<u>Issue Date</u>
1.0	New issue	Sep. 26, 2008
1.1	Add new package type Update AC data Modify Rext vs. Iout relation	Dec. 23, 2008
1.2	Add new package type	Apr. 6, 2009
1.3	Add new package type Modify Rext vs. Iout formula	Oct. 5, 2009
1.4	Updated thermal resistance and power dissipation	Feb. 3, 2010
1.5	Format modify	Oct. 19, 2010

CS8816(AF/AN/CP/AM/AN-1)

16-Bit Constant Current LED Driver with 3.0V to 5.5V Supply Voltage

■ Description

The CS8816 is a 16-Bit constant current LED driver IC which is designed for LED displays. The output current can be adjusted by using an external resistor. All outputs will have the same current drive level which is crucial in LED display application. This driver has built-in 16-bit constant current outputs, a 16-bit shift register, and a 16-bit latch circuit. These drivers have been designed by using CMOS process.

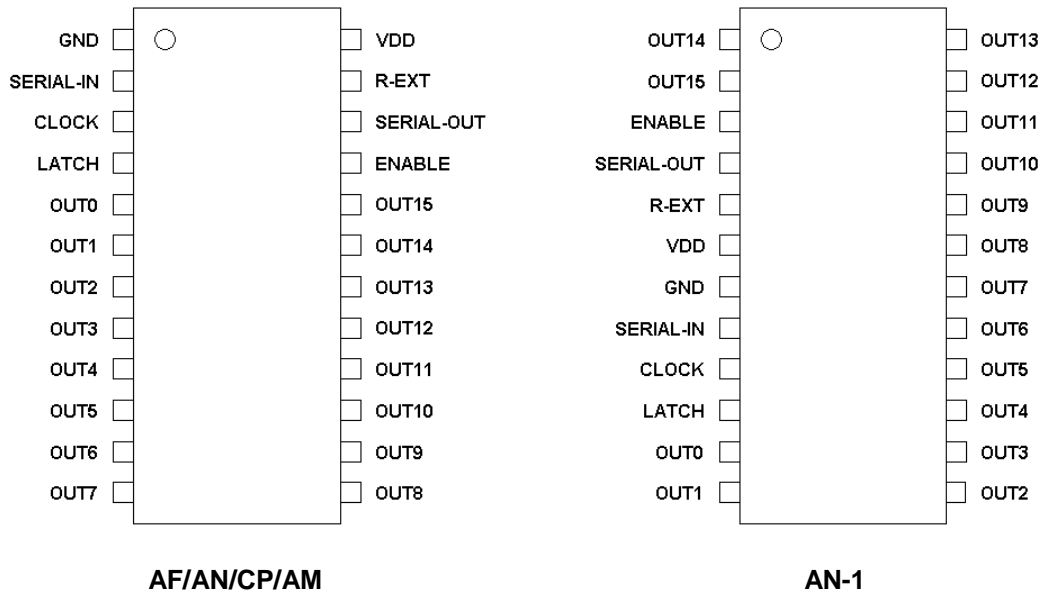
■ Feature

- Output current capability: 70mA each output
- Constant current range: 5mA to 70mA
- For common anode LED application
- Power supply voltage range VDD=3.0V to 5.5V
- Maximum output drain voltage 7.0V
- Serial data transfer rate: 25MHz(Cascade Connection)
- Operating temperature range: -40 to 85 degree C
- Output current accuracy:
 - Between Bits : < +-1.5 %
 - Between ICs: < +-4 %

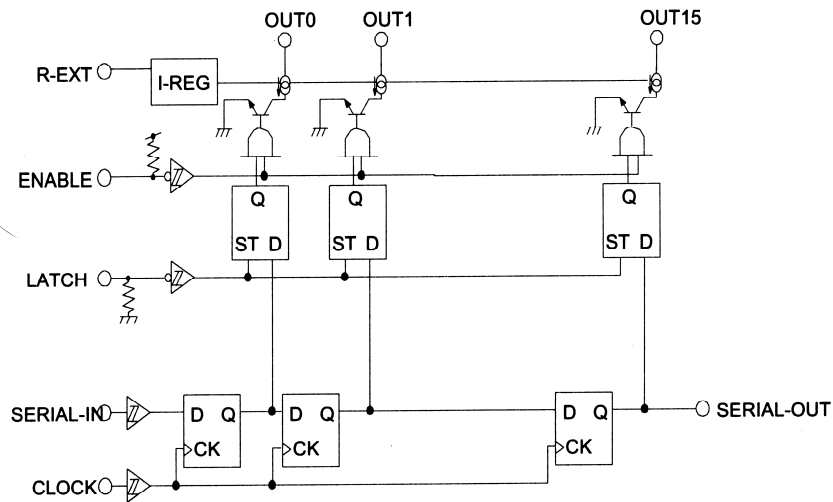
■ Product Family

- CS8816AF ----- 24SSOP(236mil, 1.0mm lead-pitch)
- CS8816AN ----- 24SSOP(150mil, 0.64mm lead-pitch)
- CS8816CP ----- 24Shrink PDIP(300mil, 1.78mm lead-pitch)
- CS8816AM ----- 24SOP(300mil, 1.27mm lead-pitch)
- CS8816AN-1 ----- 24SSOP(150mil, 0.64mm lead-pitch)

Pin Assignment



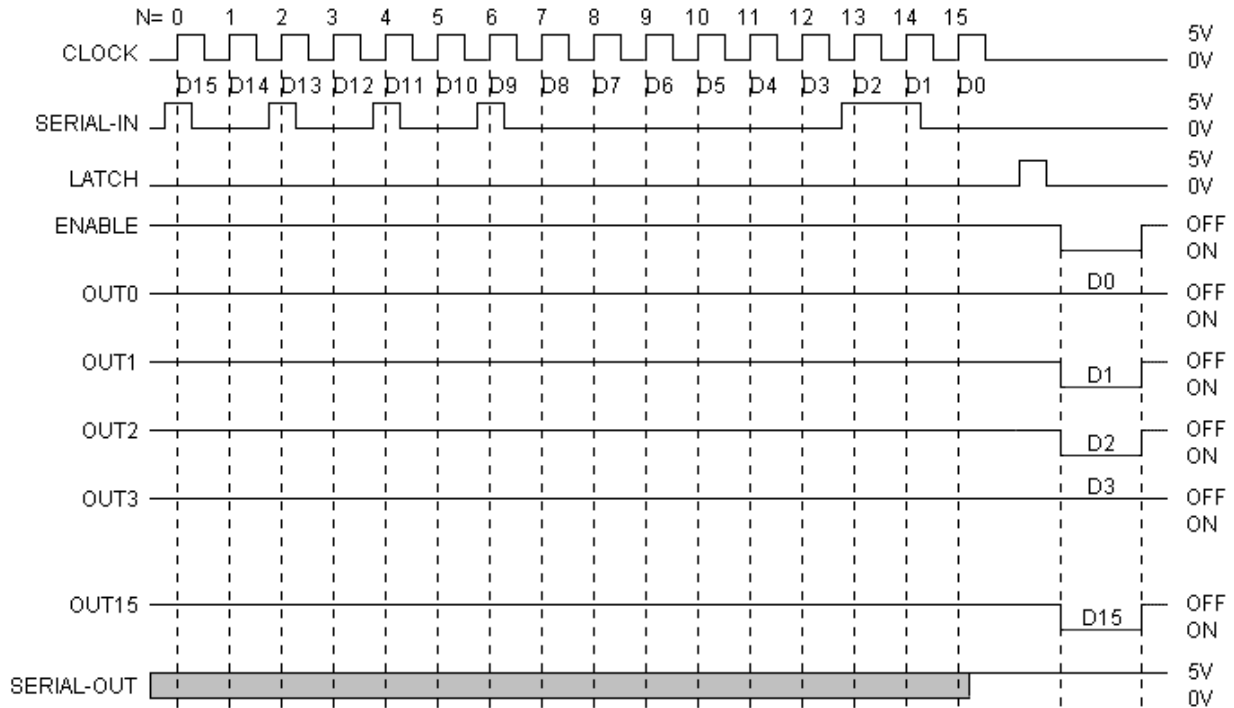
Block Diagram



Truth Table

CLOCK	LATCH	ENABLE	SERIAL-IN	OUT0---OUT7---OUT15	SERIAL-OUT
Positive edge	H	L	Dn	/Dn---/Dn-7---/Dn-15	Dn-15
Positive edge	L	L	Dn+1	No Change	Dn-14
Positive edge	H	L	Dn+2	/Dn+2---/Dn-5---/Dn-13	Dn-13
Negative edge	X	L	Dn+3	/Dn+2---/Dn-5---/Dn-13	Dn-13
Negative edge	X	H	Dn+3	Off	Dn-13

■ Timing Diagram



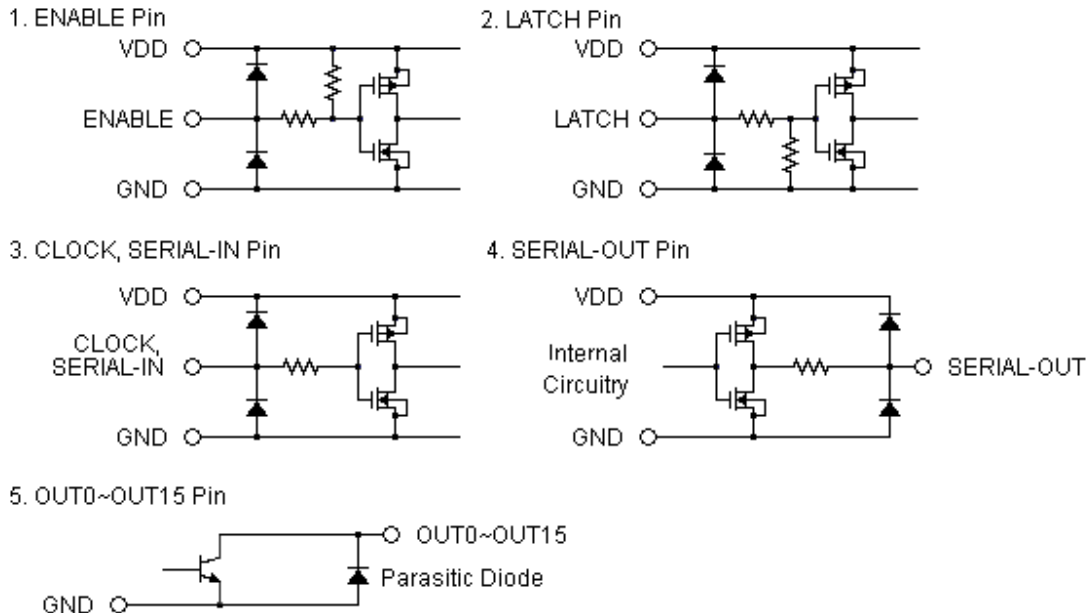
Note:

1. The latch circuit is a level-latch, not an edge-triggered latch.
2. The latch circuit holds data when LATCH pin low. When the LATCH pin is at high-level, the latch circuit passes the data from input to output. When ENABLE pin is at low-level, the latch is data transferred to the output pin OUT0~OUT15. When ENABLE pin is at high-level, the OUT0~OUT15 is turned off regardless of the latch data.

■ Pin Description

Pin No.	Pin Name	Function
1	GND	GND Pin.
2	SERIAL-IN	Serial input data pin.
3	CLOCK	Clock input terminal for shift register, rising edge trigger.
4	LATCH	Data latch input pin. When LATCH=High-level, data is passed to OUT0~OUT15, when LATCH=Low-level, data is latched.
5~20	OUT0~OUT15	16 constant current output pin to drive common anode LEDs.
21	ENABLE	Data output enable pin, when ENABLE=High-level, all OUT0~OUT15 are turned off, and when ENABLE=Low-level, all OUT0~OUT15 are enabled.
22	SERIAL-OUT	Serial data output pin for cascade operation.
23	R-EXT	The external resistor connection pin to adjust the output current.
24	VDD	3.0V~5.5V supply voltage pin.

■ Equivalent Circuits of I/O Pins



■ Absolute Maximum Ratings

Characteristics	Symbol	Rating	Unit
Supply Voltage	VDD	+7.0	V
Input Voltage	Vin	-0.4 to VDD+0.4	V
Output Current	Iout	+70	mA
Output Voltage	Vout	-0.5 to 7.0	V
GND Pin Current	IGND	1120	mA
Clock Frequency	fCLK	25	MHz
Power Dissipation (On PCB, Ta=45C)	Pd	AF: 2.36 AN: 1.94 CP: 1.91 AM: 1.76	W
Thermal Resistance (On PCB, Ta=45C)	Rth(j-a)	AF: 44.4 AN: 54.25 CP: 55.07 AM: 59.6	°C/W
Operating Temperature	Top	-40 to 85	°C
Storage Temperature	Tstg	-55 to 150	°C

■ Recommended Operating Condition

Characteristics	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage	VDD		3.0	5.0	5.5	V
Output Voltage	VOUT				7.0	V
Output Current	IOUT	OUTn			70	mA
	IOL	SERIAL-OUT Vol=0.5V			2.5	
	IOH	SERIAL-OUT Voh=4.3V			-2.0	
Input Voltage	VIH		0.7VDD		VDD+0.3	V
	VIL		-0.3		0.3VDD	
Clock Frequency	fCLK	VDD=5.0V, Cascade connection VDD=3.0V, Cascade connection			25 20	MHz
Latch Pulse Width	twLatch	VDD=4.5V ~ 5.5V	15			ns
Clock Pulse Width	twCLOCK	VDD=4.5V ~ 5.5V	15			ns
Set-Up Time for Data	tSETUP3	VDD=4.5V ~ 5.5V	20			ns
Set-Up Time for Latch	tSETUP2	VDD=4.5V ~ 5.5V	15			ns
Set-Up Time for Clock	tSETUP1	VDD=4.5V ~ 5.5V	20			ns
Hold Time for Data	tHOLD	VDD=4.5V ~ 5.5V	20			ns

■ Electrical Characteristics (Temp=25°C)

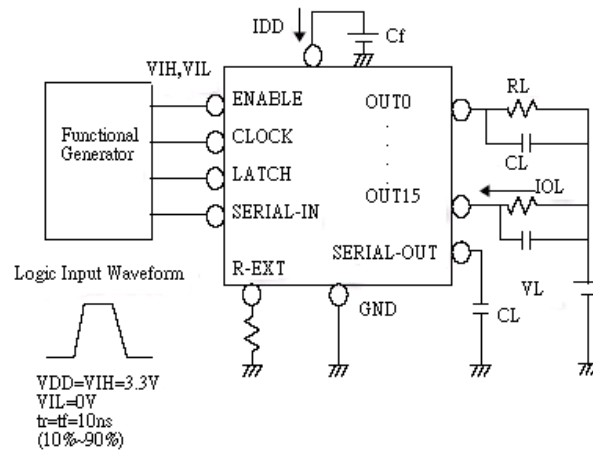
Characteristics	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage	VDD		3.0	5.0	5.5	V
Output Current	IOUT1 IOUT2	VOUT=1.0V, VDD=5.0V, R-EXT=700Ohm VOUT=1.0V, VDD=5.0V, R-EXT=3450Ohm		24.6 5.0		mA
Output Current Error Between Bits	IOUT1 IOUT2	VOUT=1.0V, R-EXT=700Ohm VOUT=1.0V, R-EXT=3450Ohm	-1.5 -1.5		+1.5 +1.5	%
Output Current Error Between Chips	ILO3 IOL4	VOUT=1.0V, R-EXT=700Ohm VOUT=1.0V, R-EXT=3450Ohm	-4 -4		+4 +4	%
Output Leakage Current	ILEAK	VOUT=5.0V			1	uA
Input Voltage Low	VIL	VDD=5.0V	0		1.5	V
Input Voltage High	VIH	VDD=5.0V	3.5		5.0	V
Output Voltage SOUT	VOL VOH	IOL=+1.5mA, VDD=5.0V IOH=-1.5mA, VDD=5.0V		4.3	0.5	V
Pull-Up Resistor	R(UP)	ENABLE Pin			202	KOhm
Pull-Down Resistor	R(DOWN)	LATCH Pin			128	KOhm
Supply Current(Off) (OUT0~OUT15 Off)	IDD(Off)	VDD=5.0V, R-EXT=700Ohm VDD=5.0V, R-EXT=3450Ohm VDD=5.0V, R-EXT=Open		3.7 0.9 0.2		mA
Supply Current(On) (OUT0~OUT15 On)	IDD(On)	VDD=5.0V, R-EXT=700Ohm VDD=5.0V, R-EXT=3450Ohm		3.7 0.9		mA

■ **Switching Characteristics** (Temp=25°C, VDD=5V, VIH=3.5V, VIL=0V, R-EXT=860Ohm)

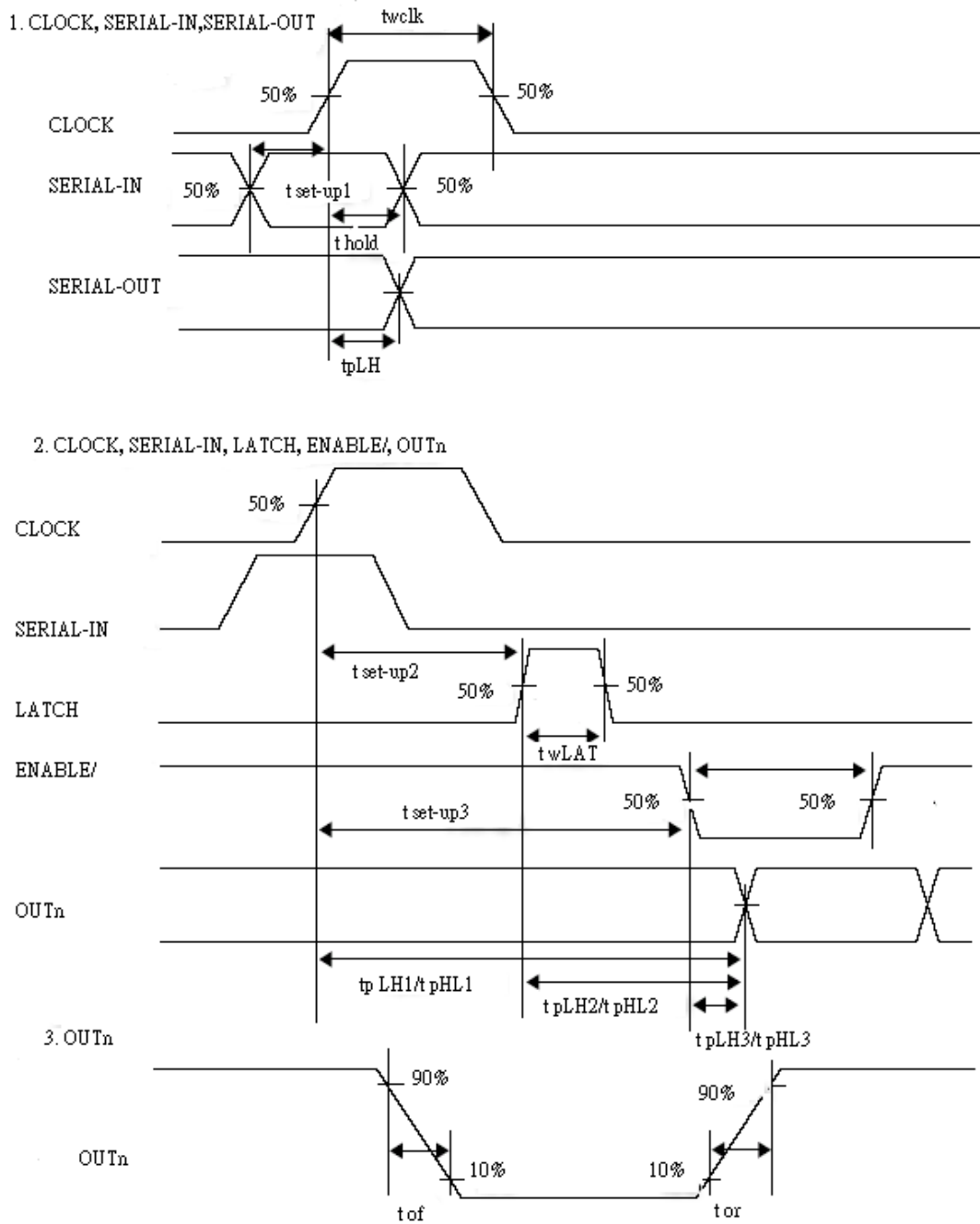
Characteristics	Symbol	Condition	Min	Typ	Max	Unit
Propagation Delay	tpLH1	CLK-OUTn, LATCH="H", ENABLE="L"		40	60	ns
	tpLH2	LATCH-OUTn, ENABLE="L"		35	50	ns
	tpLH3	ENABLE-OUTn, LATCH="H"		20	30	ns
	tpLH	CLK-SERIAL OUT		30	40	ns
	tpHL1	CLK-OUTn, LATCH="H", ENABLE="L"		80	125	ns
	tpHL2	LATCH-OUTn, ENABLE="L"		75	120	ns
	tpHL3	ENABLE-OUTn, LATCH="H"		130	180	ns
	tpHL	CLK-SERIAL OUT		30	40	ns
Pulse Width	tW(CLOCK)	CLOCK	15			ns
	tW(LATCH)	LATCH	10			ns
	tW(ENABLE)	ENABLE	180			ns
Output Rise Time	tor	Voltage waveform 10%~90%	30	75	150	ns
Output Fall Time	tof	Voltage waveform 90%~10%	10	20	40	ns
Max CLK Rise Time	tr				480	ns
Max CLK Fall Time	tf				480	ns

■ **Test Circuit**

(RL=162Ohm, CL=10pf, VL=5.0V)

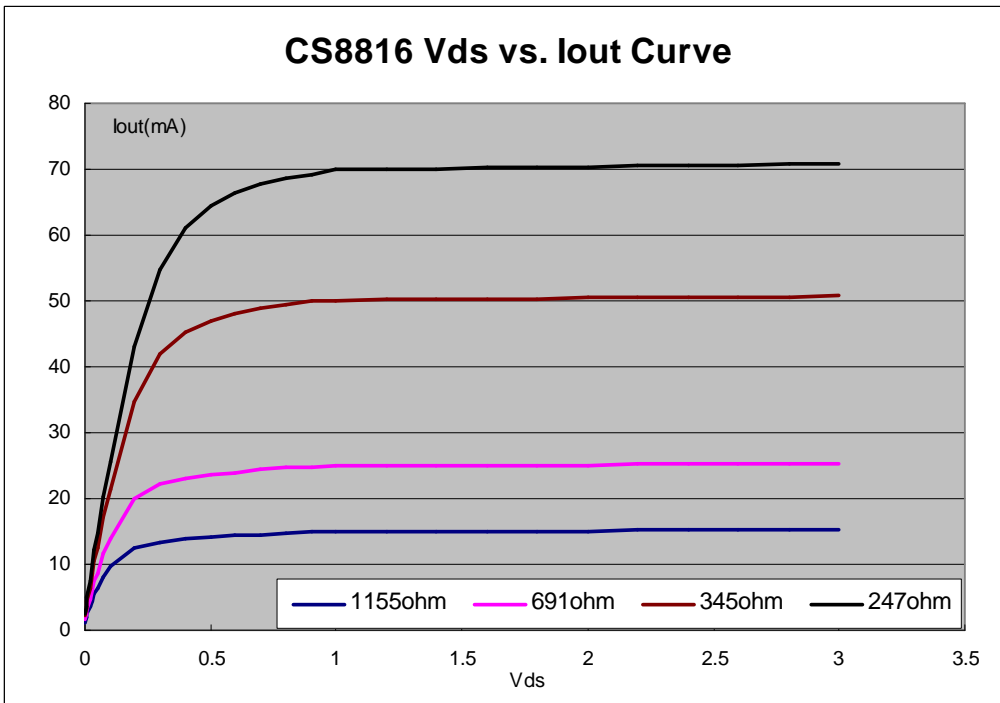
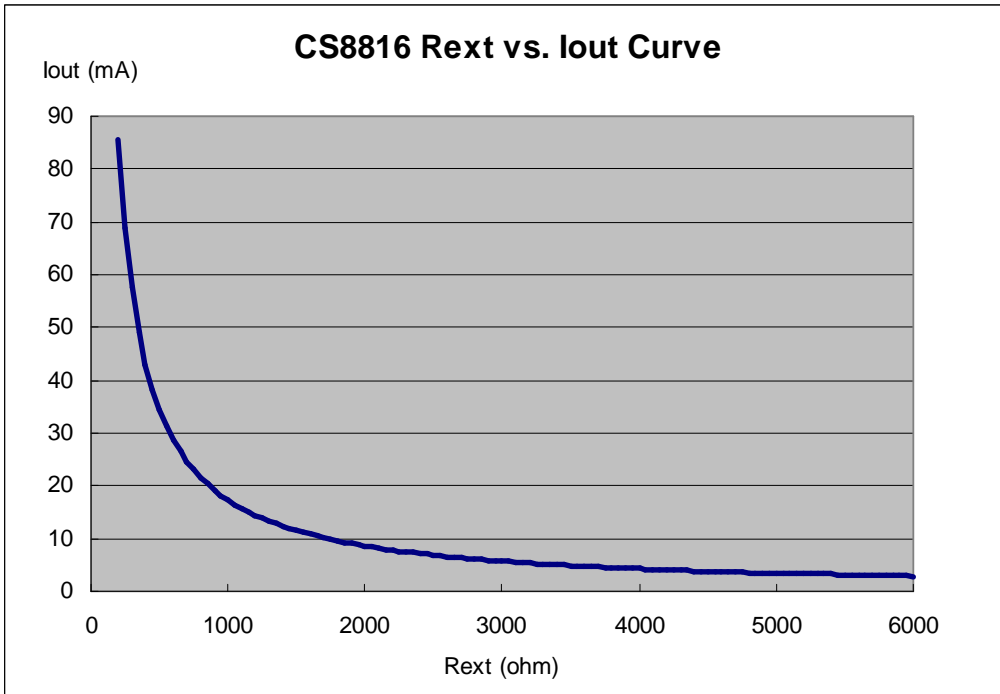


■ Timing Waveform



■ Output Current vs. R-EXT (VDD=5V)

$$I_{out} = (1.22/R_{ext}) \times 14.62$$



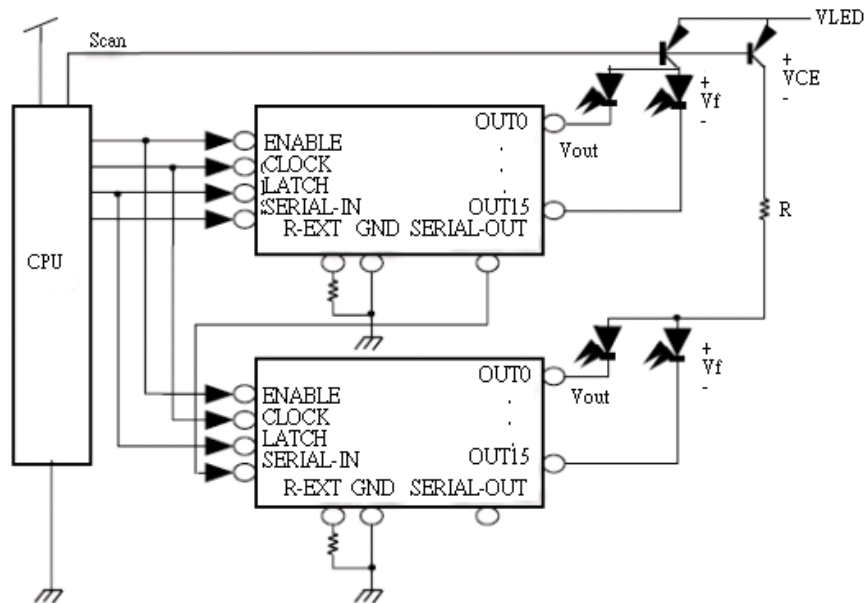
■ Typical Application

LED supply voltage is set-up by following equation:

$$V_{LED} = V_{CE} + V_f + V_o$$

To prevent too much power dissipated by driver due to the higher VLED, an additional R can be introduced to reduce the Vo when output is consuming current.

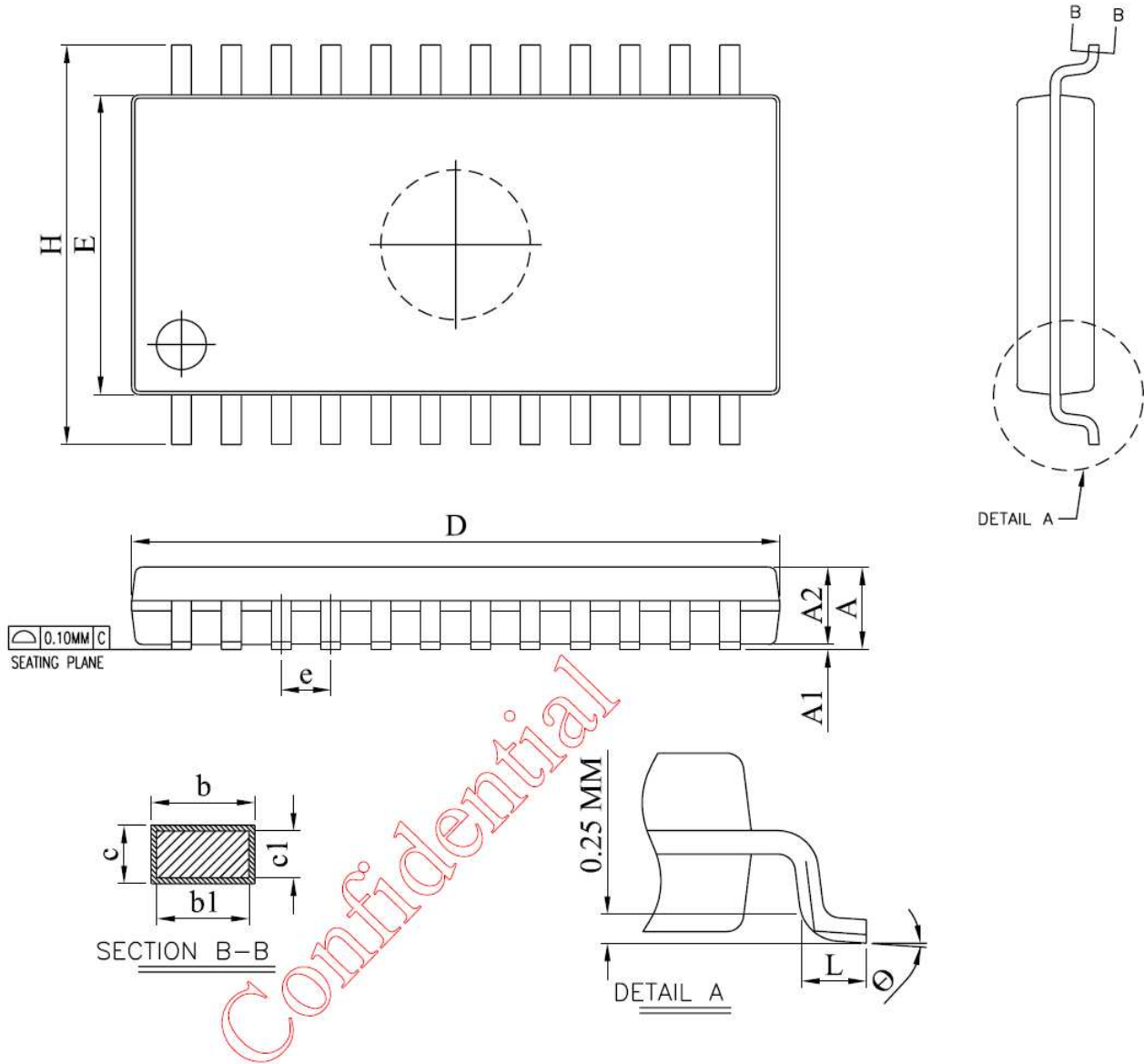
$$R = (V_{LED} - V_{CE} - V_f - V_o \text{ min}) / (I_o \text{ max} * \text{Bit max})$$



■ Order Information

Part No.	Package Type	Lead Pitch
CS8816AF	24SSOP(236mil)	1.0mm
CS8816AN	24SSOP(150mil)	0.64mm
CS8816CP	24Shrink PDIP(300mil)	1.78mm
CS8816AM	24SOP(300mil)	1.27mm
CS8816AN-1	24SSOP(150mil)	0.64mm

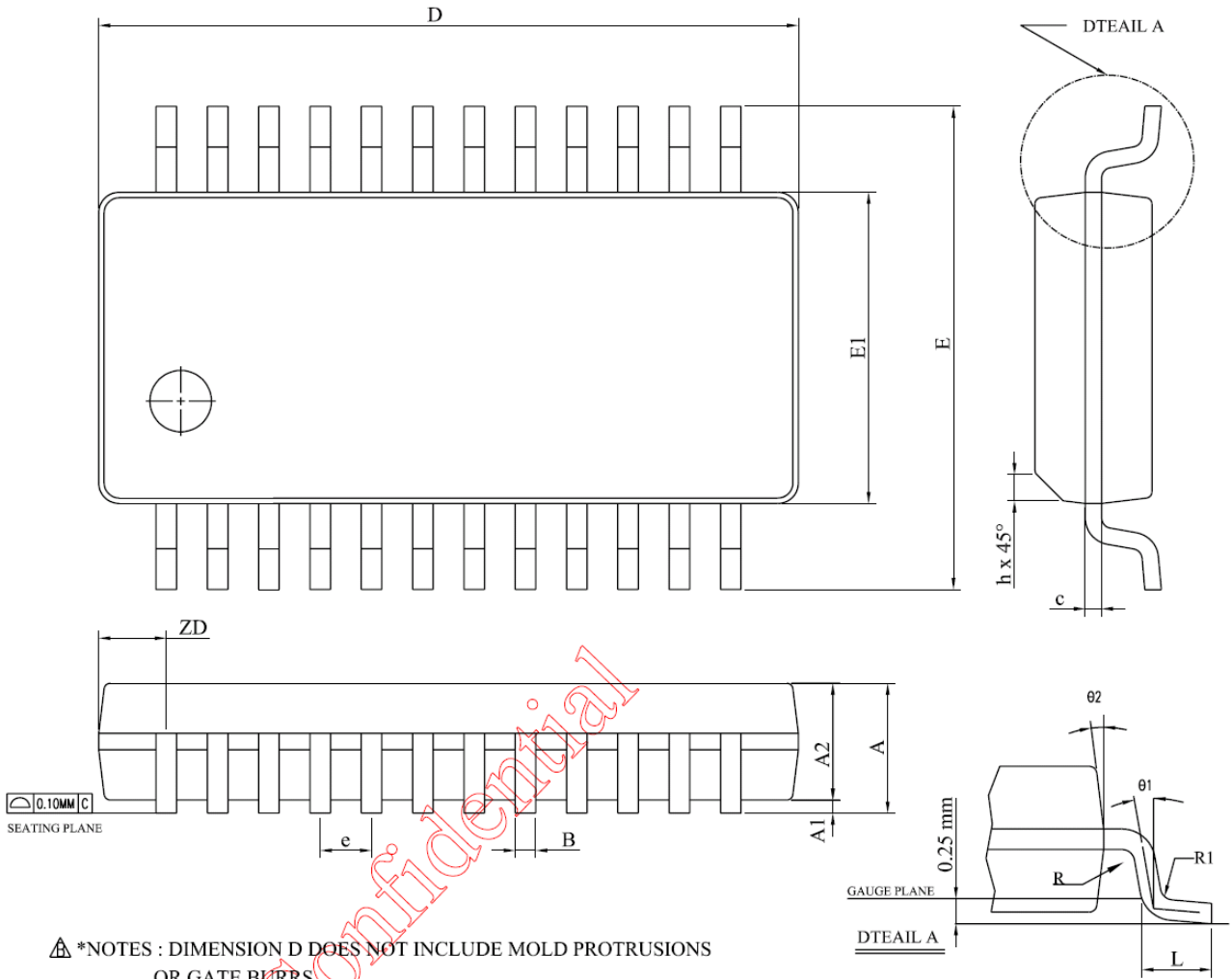
Title: Package outline for 24 SSOP-236 mil



Note: Plating thickness spec : 0.3 mil ~ 0.8 mil.

SYMBOL		A	A1	A2	b	b1	c	c1	D	e	E	H	L	θ°
mm	Min.	-	0.05	1.30	0.30	0.30	0.10	0.10	12.80	1.00 BSC	5.80	7.70	0.25	0
	Nom.	-	0.10	1.50	0.40	0.40	0.15	0.15	13.00		6.00	8.00	0.45	-
	Max.	1.90	0.15	1.70	0.52	0.50	0.27	0.25	13.20		6.20	8.30	0.65	10

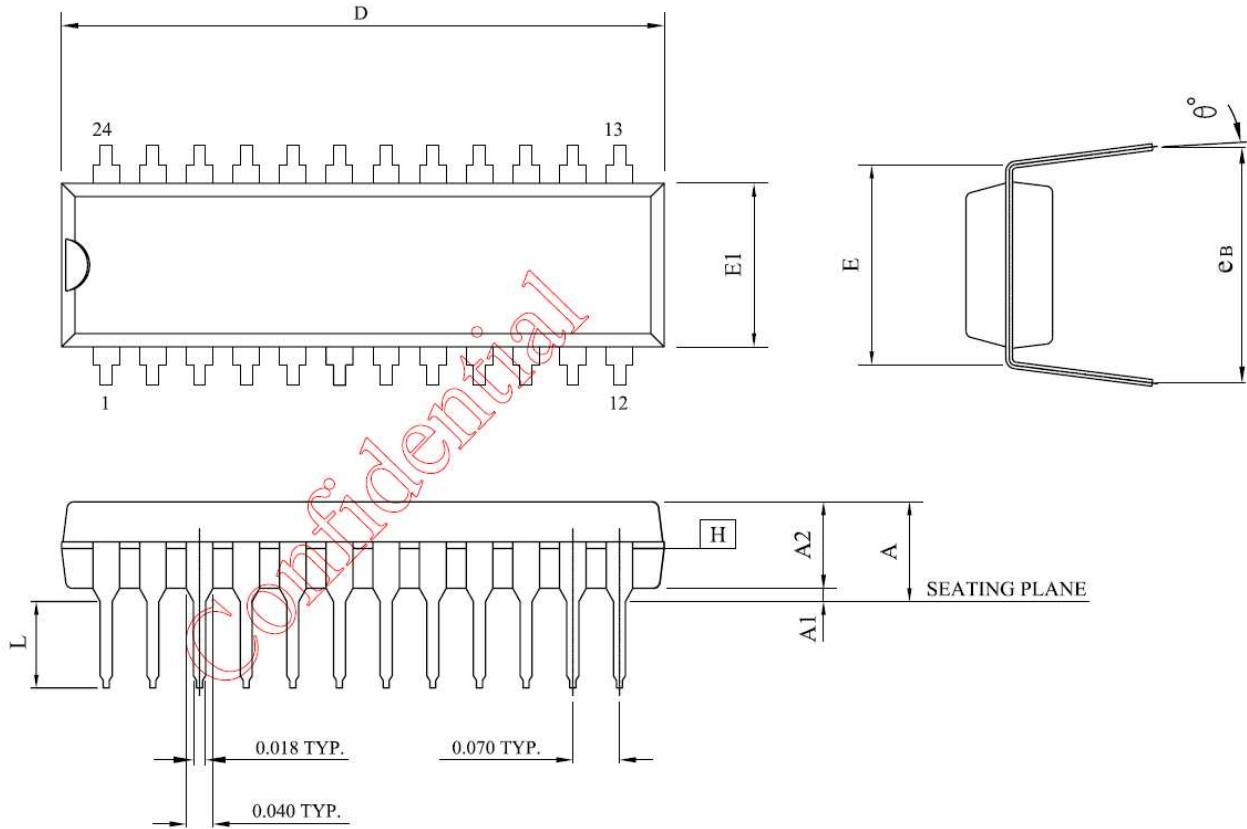
Title: Package outline for 24 SSOP-150 mil



***NOTES :** DIMENSION D DOES NOT INCLUDE MOLD PROTRUSIONS OR GATE BURRS.
MOLD PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 0.006 INCH PER SIDE.
Plating thickness spec : 0.3 mil ~ 0.8 mil.

SYMBOL		A	A1	A2	B	c	e	D	E	E1	L	h	ZD	R1	R	θ	θ1	θ2		
UNIT																				
mm	Min.	1.35	0.10	-	0.20	0.18	0.635 BSC	8.56	5.79	3.81	0.41	0.25	0.838 REF	0.20	0.20	0°	0°	5°		
	Nom.	1.63	0.15	-	-	-		8.66	5.99	3.91	0.635	-		-	-	-	-	-	-	10°
	Max.	1.75	0.25	1.50	0.30	0.25		8.74	6.20	3.99	1.27	0.50		0.33	-	8°	-	-	15°	

Title: Package outline for 24Shrink PDIP-300mil (Pitch 0.07 inch)

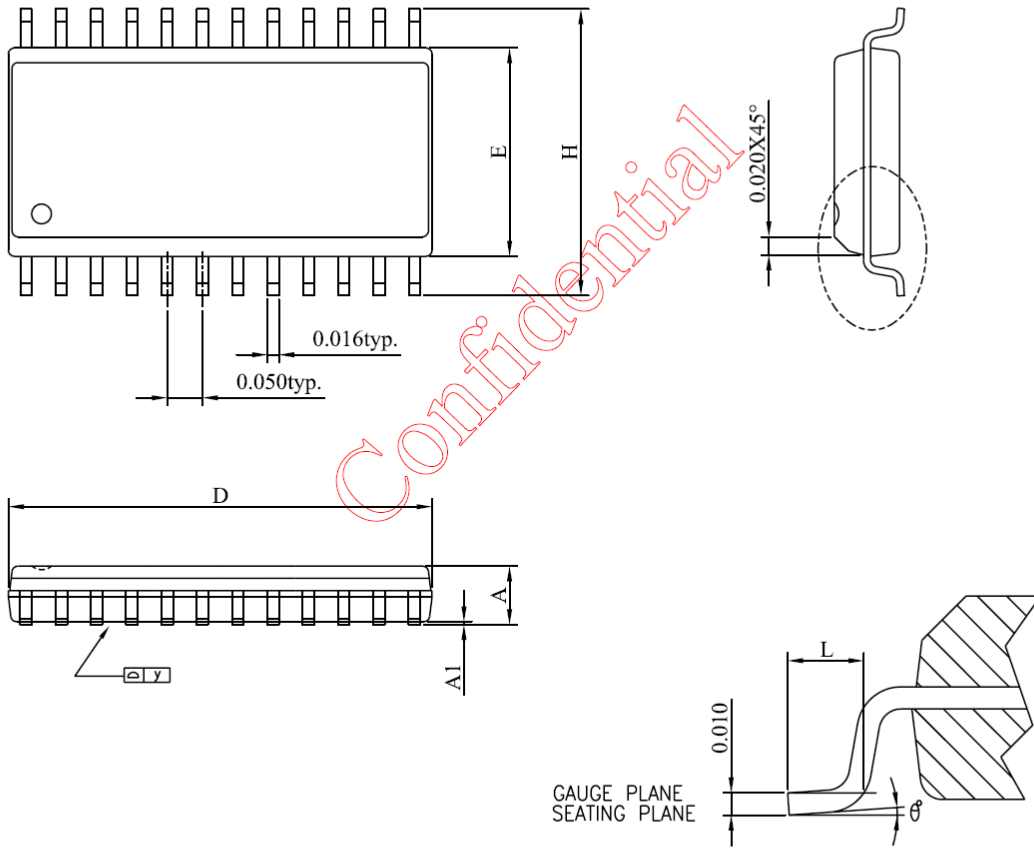


NOTES:

1. JEDEC OUTLINE : MS-019 AF
2. "D", "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH.
3. eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
4. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
5. DISTANCE BETWEEN LEADS INCLUDING DAM BAR PROTRUSIONS TO BE .005 INCH MINIMUM.
6. DATUM PLANE [H] COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY.
7. PLATING THICKNESS : 0.3 ~ 0.8 MIL.

SYMBOL		A	A1	A2	D	E	E1	L	e _B	θ°
UNIT										
inch	Min.	-	0.015	0.125	0.880	0.300 BSC.	0.245	0.115	0.335	0°
	Nom.	-	-	0.130	0.900		0.250	0.130	0.355	7°
	Max.	0.210	-	0.135	0.920		0.255	0.150	0.375	10°

Title: Package outline for 24L SOP-300mil



Note: Plating thickness spec : 0.3 mil ~ 0.8 mil.

SYMBOL		A	A1	D	E	H	L	θ°
inch	Min.	-	0.004	0.599	0.291	0.394	0.016	0
	Nom.	-	-	0.600	0.295	0.406	0.035	4
	Max.	0.104	-	0.624	0.299	0.419	0.050	8